1.

Record Nr.	UNINA990008689010403321
Autore	Sondhaus, Lawrence
Titolo	Franz Conrad von Hötzendorf : l'anti Cadorna / Lawrence Sondhaus ; traduzione di Alessandra Di Poi
Pubbl/distr/stampa	Gorizia : LEG, 2003
ISBN	88-86928-59-9
Descrizione fisica	368 p. : ill. ; 21 cm
Collana	Le guerre : storie di uomini, armi, atti di forza ; 14
Disciplina	355.0092
Locazione	FSPBC
Collocazione	Collez. 2110 (14)
Lingua di pubblicazione	Italiano
Formato	Materiale a stampa
Livello bibliografico	Monografia

2. Record Nr.	UNINA9910811577503321
Titolo	11th international congress molded interconnect devices : scientific proceedings : selected, peer reviewed papers from the 11th International Congress Molded Interconnect Devices (MID 2014), September 24-25, 2014, Nuremberg / Fuerth, Germany / / edited by Jorg Franke [and three others]
Pubbl/distr/stampa	Pfaffikon, Switzerland : , : TTP, , 2014 Enfield, New Hampshire : , : Trans Tech Publications Ltd, , [date of distribution not identified] ©2014
ISBN	3-03826-636-1
Descrizione fisica	1 online resource (119 p.)
Collana	Advanced Materials Research, , 1662-8985 ; ; Volume 1038
Disciplina	621.367
Soggetti	Molded interconnect devices Three-dimensional display systems
Lingua di pubblicazione	Inglese
Formato	Materiale a stampa
Livello bibliografico	Monografia
Note generali	Description based upon print version of record.
Nota di bibliografia	Includes bibliographical references at the end of each chapters and index.
Nota di contenuto	11th International Congress Molded Interconnect Devices - Scientific Proceedings; Preface and Committees; Table of Contents; Chapter 1: Development and Prototyping; Method for the Identification and Comparison of Alternative Process Chains Focusing on Economics Efficiency Analysis during the Conceptual Design of Mechatronic Integrated Devices; Novel Approach for the Implementation of 3D-MID Compatible Routing Functionalities into Computer-Aided Design Tools; Optimized Process Sequences for Prototyping of Molded Interconnect Devices; Integration of Functional Circuits into FDM Parts Chapter 2: Printing TechnologiesPrinting of Functional Structures on Molded 3D Devices; Electrical Functionalization of Thermoplastics by Combining Plasmadust Coating and Aerosol Jet Printing; Production of Miniaturized Sensor Structures on Polymer Substrates Using Inkjet Printing; Progress in the Manufacturing of Molded Interconnected Devices by 3D Microcontact Printing; Chapter 3: Materials and Manufacturing; Characterization of Electromagnetic Properties of MID

Materials for High Frequency Applications up to 67 GHz

Novel Laser Induced Metallization for Three Dimensional Molded Interconnect Device Applications by Spray MethodExperimental Investigation of Laser Sintering of Conductive Adhesive for Functional Prototypes Produced by Embedding Stereolithography; MID Fabricated by Ultrasonic Processing; Usage of Industrial Robots as Flexible Handling Devices Supporting the Process of Three Dimensional Conductive Pattern Generation; Chapter 4: Manufacturing Processes; Study of MID Technologies for Automotive Lighting and Light Signaling Devices; Chapter 5: Assembly Technologies and Inspection

Design and Solder Process Optimization in MID Technology for High Power ApplicationsChapter 6: Quality and Reliability; Hot Pin Pull Method - New Test Procedure for the Adhesion Measurement for 3D-MID; Keywords Index; Authors Index

Sommario/riassunto

Collection of selected, peer reviewed papers from the 11 th International Congress Molded Interconnect Devices (MID 2014), September 24-25, 2014, Nuremberg / Fuerth, Germany. The 16 papers are grouped as follows: Chapter 1: Development and Prototyping, Chapter 2: Printing Technologies, Chapter 3: Materials and Manufacturing, Chapter 4: Manufacturing Processes, Chapter 5: Assembly Technologies and Inspection, Chapter 6: Quality and Reliability.

3. Record Nr.	UNISA996417553503316
Titolo	The Nikkei weekly
Pubbl/distr/stampa	Tokyo, Japan, : Nihon Keizai Shimbun, 1991-
Descrizione fisica	1 online resource
Disciplina	330.95204
Soggetti	83.50 national monetary economics Conditions économiques Hebdomadaires Commerce Economic history Financiën Economische situatie Periodicals. Japan Commerce Periodicals Japan Economic conditions Periodicals Japan Commerce United States Periodicals United States Commerce Japan Periodicals Etats-Unis d'Amérique Japon Japan United States
Lingua di pubblicazione	Inglese
Formato	Materiale a stampa
Livello bibliografico	Periodico
Note generali	"Japan's leading business newspaper." Title from caption.